

## CBR02C669B3GAC

CBR-SMD RF COG, Ceramic, 6.6 pF, +/-0.1 pF, 25 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0201



Click [here](#) for the 3D model.

Dimensions	
Chip Size	0201
L	0.6mm +/-0.03mm
W	0.3mm +/-0.03mm
T	0.3mm +/-0.03mm
B	0.15mm +/-0.05mm

  

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	15000

General Information	
Series	CBR-SMD RF COG
Style	SMD Chip
Description	SMD, Fixed, RF, Ultra High Q, Low ESR, Class I
Features	Ultra High Q, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	0.3 mg
Notes	Solder Reflow Only.
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	6.6 pF
Capacitance Tolerance	+/-0.1 pF
Voltage DC	25 VDC
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Dissipation Factor	0.188%
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	10 GOhms
Quality Factor	532

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